



# 2Z2835AW35DFZQN2

- **♦**Outline(L\*W\*H): 3.5\*2.8\*0.7 mm
- ♦ High flux efficiency & offer a middle power 0.5W
- **◆**Good thermal dissipation & optical uniformity

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#### **Features**

- Forward current: ≤150mA
- Typical view angle 50% Iv: 120°
- RoHS and REACH-compliant
- Lens color: yellowish
- Qualified according to JEDEC moisturevity
- ESD level 6KV(HBM)

# **Applications**

- Indoor signage display applications
- Indoor decorating and entertainment design
- Flat backlight for LCD. Switch and symbol
- Indicator and backlighting for all consumer electronics





#### **■ Product Code Method**

2 - Z - 2835 -A- W35D - F - Z - Q - N -2

① ② ③ ④

6 7 8 9 10

1	2	3	4	5
Process Type	Category	Lead Frame Size	View Angle	Dice Wavelength &Luminous Rank
2: the standard of	Z: SMD power	2835: 2.8* 3.5mm	A: 120°	Wxxx: White
energy star	LED			

6	7	8	9	(10)
Bracket or COB Specifications	CRI or Zener Code	Assembly Code	After the Station Process Code	Spectral Condition Code
F: bracket code	Z: zener	Q: company code for different meaning	N: PLCC procedure	2: 150mA for testing

# ■ Maximum Rating(Ta=25°C)

Characteristics	Symbol	Rating	Unit
DC forward current	$I_{\mathrm{F}}$	150	mA
Pulse forward current*3	$I_{ m PF}$	240	mA
Reverse voltage	$V_R$	5	V
Junction temperature	$T_{ m J}$	110	°C
Operating temperature range	$T_{OP}$	-40-85	°C
Storage temperature range	$T_{STG}$	-40-100	°C
Soldering temperature*4	$T_{SD}$	260	°C

Notes 1: There is no maximum or typical voltage parameter

2: For other ambient, limited setting of current will be depended on de-rating curves.

3: Duty 1/10, pulse width 0.1ms

4: The maximum of soldering time is 5 seconds in  $T_{\text{SD}}$ 

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# **■** Typical Product Characteristics (Ta=25°C)

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Characteristics	Symbol	Min.	Тур.	Max.	Unit	Test condition
Forward Voltage	$V_{\mathrm{F}}$	2.8	3.2	3.6	V	I <sub>F</sub> =150mA
Reverse Current	$I_R$	-	-	10	μΑ	V <sub>R</sub> =5V
Luminous Lumen	Φ	50	58	-	lm	I <sub>F</sub> =150mA
View Angle	$2\theta_{1/2}$	-	120	-	deg	I <sub>F</sub> =150mA
Color Coordinate	X	-	0.3467	-	-	I —150m A
Color Coordinate	у	-	0.3526	-	-	$I_F=150mA$
Color Rendering Index	CRI	70	-	-	-	I <sub>F</sub> =150mA
Color Temperature	CCT	5710	-	6530	K	I <sub>F</sub> =150mA

Notes: 1. Measurement Errors:

Forward Voltage:  $\pm 0.1$ V, Luminous Lumen:  $\pm 10\% \Phi$ , View Angle:  $\pm 5\%$ , Color Coordinate  $(x, y) \pm 0.006$ 

Color Rendering Index: ±5, Color Temperature: ±10%

2. Electrical-Optical characteristics (Ta=25°C)

#### **■** Range of Bins

# 1). Forward Voltage Bins (I<sub>F</sub>=150mA)

Bin Code	Min. V <sub>F</sub> (V)	Min. V <sub>F</sub> (V)
В	2.8	2.9
С	2.9	3.0
D	3.0	3.1
Е	3.1	3.2
F	3.2	3.3
G	3.3	3.4
Н	3.4	3.5
1	3.5	3.6

# 2). Luminous Lumen Bins (I<sub>F</sub>=150mA)

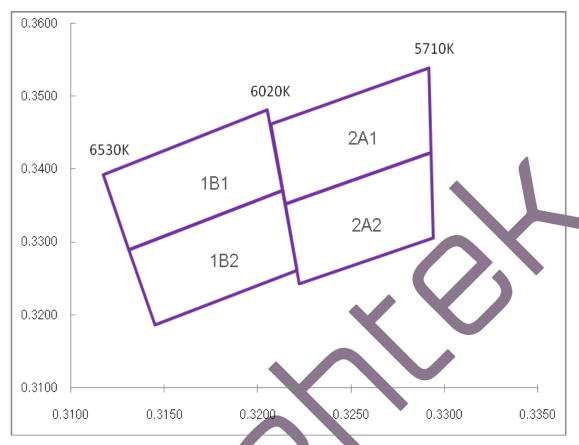
Bin Code	Min. Φ (lm)	Max. Φ (lm)
25	50	55
26	55	60
27	60	65

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# **■** Color Coordinate Comparison

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#### **Color Rank**

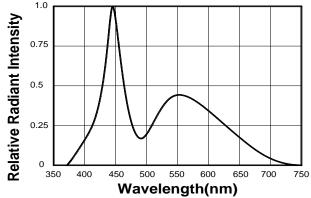
BIN	X	y	BIN	X	у
	0.3205	0.3481		0.3292	0.3539
1B1	0.3117	0.3393	2A1	0.3207	0.3462
IDI	0.3131	0.3290	2 <b>A</b> 1	0.3215	0.3353
X	0.3213	0.3371		0.3293	0.3423
	0.3213	0.3371		0.3293	0.3423
1B2	0.3131	0.3290	2A2	0.3215	0.3353
162	0.3145	0.3187		0.3222	0.3243
	0.3221	0.3261		0.3294	0.3306



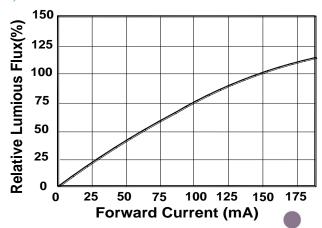
### **■** Electrical-Optical Characteristics

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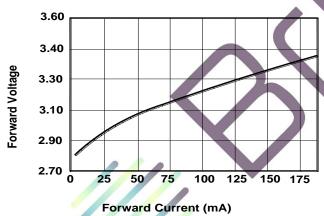
### 1). Relative Spectral Distribution



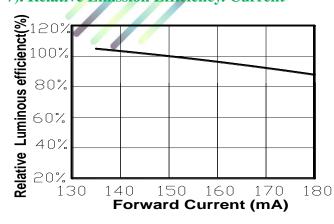
#### 3).Relative Luminous Flux .Current



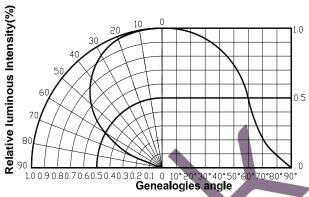
#### 5). Electrical Characteristics



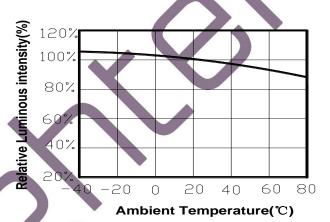
# 7). Relative Emission Efficiency. Current



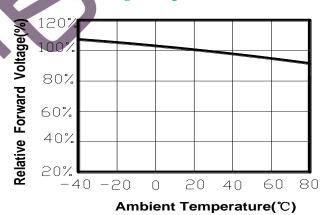
#### 2). Typical Spatial Distribution



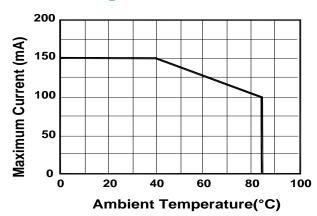
#### 4). Relative Luminous Flux Ambient Temperature



Forward Voltage Temperature

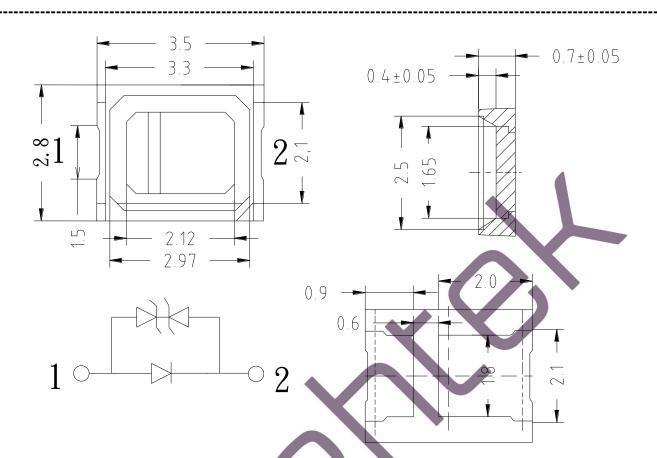


#### 8). Thermal Design

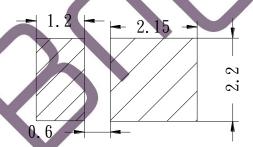




### Dimensions



# **Recommend Pad layout**



Notes: 1. All dimensions are in millimeters

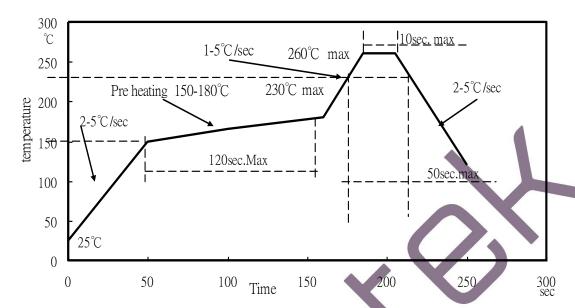
- 2. Tolerance is  $\pm 0.1$ mm unless otherwise noted
- 3. Specifications are subject to change without notice.



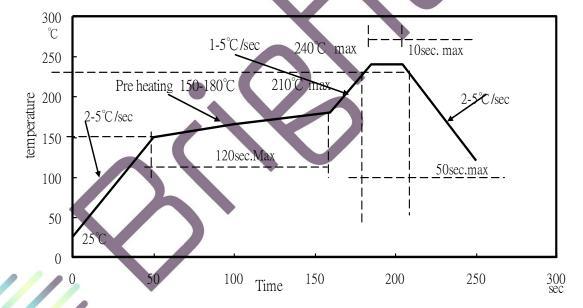
#### **■** Reflow Profile

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#### 1. I<sub>R</sub> reflow soldering Profile for Lead Free solder



#### 2. I<sub>R</sub> reflow soldering Profile for Lead solder



**Notes:** 

- 1. We recommend the reflow temperature  $240^{\circ}\text{C}$  ( $\pm 5^{\circ}\text{C}$ ).the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
- 2. Don't cause stress to the silicone resin while it is exposed to high temperature.
- 3. Number of reflow process shall be less than 3 times.

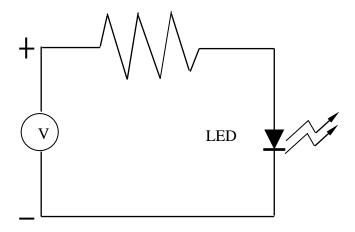
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### **■** Test Circuit and Handling Precautions

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#### 1. Test circuit



#### 2. Handling precautions

#### 2.1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2.2. Storage

1). It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature:  $5^{\circ}\text{C} \sim 30^{\circ}\text{C} (41^{\circ}\text{F} \sim 86^{\circ}\text{F})$ 

2). Shelf life in sealed bag: 12 month at  $<5^{\circ}\text{C} \sim 30^{\circ}\text{C}$  and <60% R.H. after the package is Opened, the products should be used within a weeks or they should be keeping to stored at  $\leq 20\%$  R.H. with zip-lock sealed.

# 2.3. Baking

Suggest packing open after 1 weeks, before use baking products, conditions as follows:

The Conditions are as followings:

1).  $60\pm3$ °C X 24hrs and <5%RH, for reel

2).  $125\pm3^{\circ}$ C X 2hrs, for single LED

It shall be normal to see slight color fading of carrier (light yellow) after baking in process

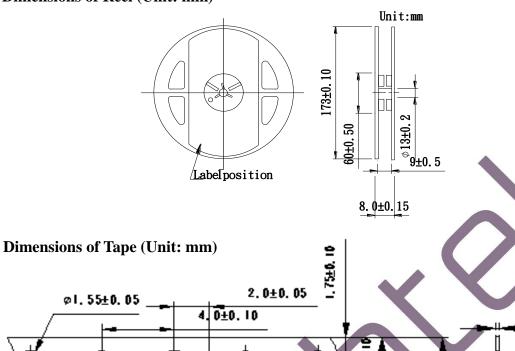
0.20



# Packing

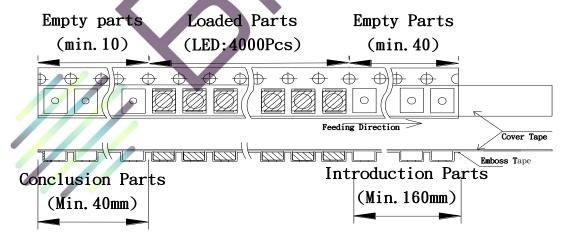
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#### • Dimensions of Reel (Unit: mm)



1.0

Arrangement of Tape



**Notes:** 

1. Empty component pockets are sealed with top cover tape

4. <u>0±</u>0.

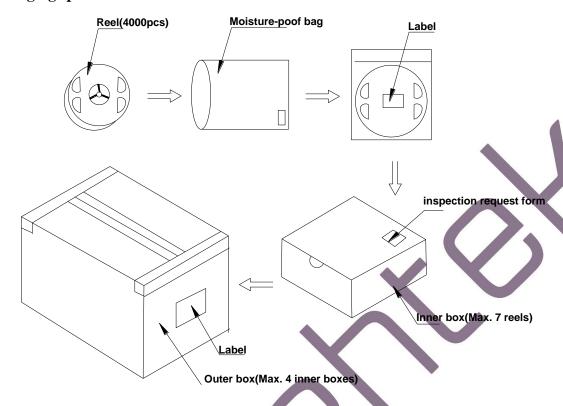
- 2. The max loss number of SMD is 2pcs
- 3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications
- 4. 4,000pcs per reel



### Packing

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#### Packaging specifications



# Notes:

Reeled product (max.4,000) is packed in a sealed moisture-proof bag. Seven bags are packed in an inner box (size: about 260 X 230 X 100 mm) and four inner boxes are in an outer box (size: about 480 X 275 X 215 mm). On the label of moisture-poof bag, there should be the information of Part No., Lot No. and quantity number; also the total quantity number should be on inspection request form on outer box.



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#### Precautions

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#### 1. Abnormal situation caused by improper setting of collet

To choose the right collet is the key issue in improving the product's quality. LED is different from other electronic components, which is not only about electrical output but also for optical output. This characteristic made LED more fragile in the process of SMT. If the collet's lowering down height is not well set, it will bring damage to the gold wire at the time of collet's picking up and loading which will cause the LED fail to light up, light up now and then or other quality problems

#### 2. How to choose the collet

During SMT, please choose the collet that has larger outer diameter than the lighting area of lens, in case that improper position of collet will damage the gold wire inside the LED. Different collets fit for different products, please refer to the following pictures cross out

# Outer diameter of collet should be larger than the lighting area



#### 3. Other points for attention

- A. No pressure should be exerted to the epoxy shell of the SMD under high temperature.
- B. Do not scratch or wipe the lens since the lens and gold wire inside are rather fragile and cross out easy to break.
- C. LED should be used as soon as possible when being taken out of the original package, and should be stored in anti-moisture and anti-ESD package.

#### 4. This usage and handling instruction is only for your reference.



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# ■ Test Items and Results of Reliability

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Test Item	Test Conditions	Duration/ Cycle	Ac/Re	Number of Damage	Reference
Normal Temperature Life	$Ta = 23^{\circ}C(\pm 5^{\circ}C)$ $I_F = 150 \text{mA}$	1008 hrs	0/1	0/22	JESD22 A-108
High Temperature Life	$Ta=85^{\circ}C(\pm 5^{\circ}C)$ $I_F=150mA$	1008 hrs	0/1	0/22	JESD22 A-108
High Humidity Heat Life	$Ta = 85^{\circ}C(\pm 5^{\circ}C)$ RH = 85% $I_{F} = 150 \text{mA}$	1008 hrs	0/1	0/22	JESD22 A-108
Thermal shock	-45°C/30min~105°C /30min (±5°C)	1008 hrs	0/1	0/22	JESD22 A-104
Electrostatic Discharge (ESD) Test	According to the SPEC	3 cycles	0/1	0/22	AEC Q101-001
Low Temperature Storage	T <sub>a</sub> =-40°C	1008 hrs	0/1	0/22	JESD22-A103D
High Temperature Storage	T <sub>a</sub> =125℃	1008 hrs	0/1	0/22	JESD22-A103D

*Criteria for Judging						
Itama	Criteria for Judgment of Par					
Item	Symbol	Condition	Min	Max		
Forward Voltage	$V_{\mathrm{F}}$	I <sub>F</sub> =150mA	-	USL* <sup>1</sup> ×1.1		
Reverse Current	$I_R$	V <sub>R</sub> = 5V	-	10μΑ		
Luminous Lumen	Ф	I <sub>F</sub> =150mA	LSL*2×0.7	-		

[Note] USL\*1: Upper Specification Level

LSL\*2: Lower Specification Level